

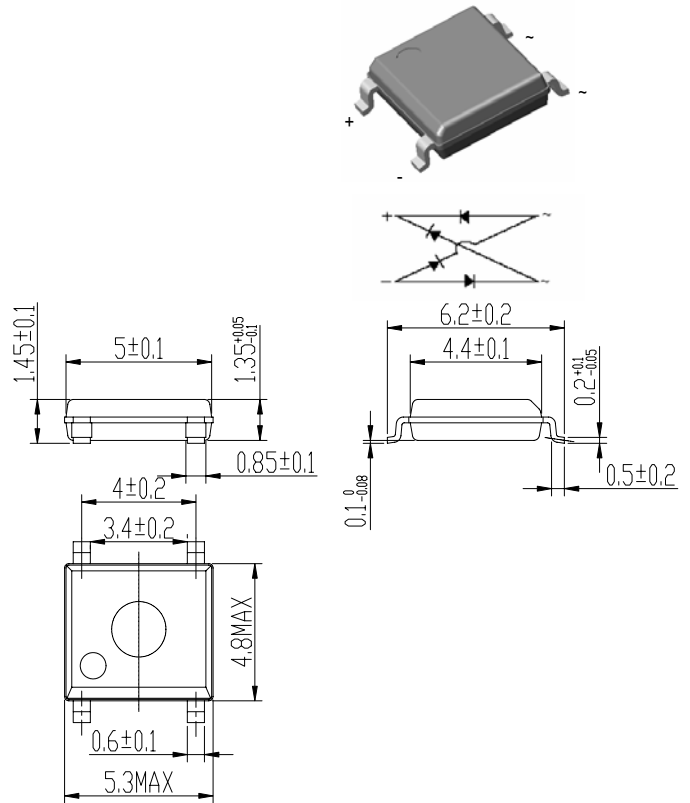


**Features**

- Low Profile: Typical height of 1.4mm
- Ideal for automated placement
- High surge current capability
- Solder Dip 260 , 40seconds

**Mechanical Data**

- Case:SOPA-4
- Epoxy meets UL-94V-0 Flammability rating
- Terminals:Matte tin plated leads, solderable per J-STD-002B and JESD22-B102D
- Polarity:As markde on body



**Maximum Ratings & Electrical Characteristics** Ratings at 25

ambient temperature unless otherwise specified.

Parameter	Symbol	LB2S	LB4S	LB6S	LB8S	Unit
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	V
Maximum RMS voltage	$V_{RMS}$	140	280	420	560	V
Maximum DC blocking voltage	$V_{DC}$	200	400	600	800	V
Maximum Average forward output rectified current on glass-epoxy P.C.B on aluminum substrate	$I_{F(AV)}$		1.0 0.8			A
Peak forward surge current 8.3 ms single sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$		30			A
Rating for fusig ( $t < 8.3ms$ )	$I^2t$		3			A <sup>2</sup> sec
Maximum instantaneous forward voltage drop per diode at 0.4A	VF		0.95			V
Maximum DC reverse current at $T_A=25$ rated DC blocking voltage per leg $T_A=125$	IR		5 500			$\mu A$
Typical thermal resistance per leg (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$		80 25			$^{\circ}W$
Operating junction temperature range	$T_J$		-55 to +150			
Storage temperature range	$T_{STG}$		-55 to +150			

- Notes: 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.
- 2. JEDEC registered values

**RATINGS AND CHARACTERISTIC CURVES**

( $T_A=25$  unless ontherwise noted)

